



## Material Content Data Sheet



<b>Sales Product Name</b>		SAK-TC1736-128F80HL AA		<b>Issued</b>		28. November 2014		
<b>MA#</b>		MA000838442						
<b>Package</b>		PG-LQFP-144-10		<b>Weight*</b>		1419.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	24.572	1.73	1.73	17314	17314
leadframe	non noble metal	magnesium	7439-95-4	0.538	0.04		379	
	inorganic material	silicon	7440-21-3	2.331	0.16		1642	
	non noble metal	nickel	7440-02-0	10.757	0.76		7579	
wire	non noble metal	copper	7440-50-8	344.930	24.30	25.26	243048	252648
	noble metal	gold	7440-57-5	6.501	0.46	0.46	4580	4580
	encapsulation	organic material	carbon black	1333-86-4	5.065	0.36		3569
encapsulation	plastics	epoxy resin	-	136.751	9.64		96359	
	inorganic material	silicondioxide	60676-86-0	871.151	61.39	71.39	613840	713768
leadfinish	non noble metal	tin	7440-31-5	9.120	0.64	0.64	6426	6426
plating	noble metal	silver	7440-22-4	3.047	0.21	0.21	2147	2147
glue	plastics	epoxy resin	-	1.106	0.08		779	
	noble metal	silver	7440-22-4	3.319	0.23	0.31	2338	3117
*deviation	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

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